

WW25R

±1%, ±5%, 2W

Metal plate low ohm power chip resistors Size 2512 (6432) Current Sensing Type Automotive AEC Q200 compliant

*Contents in this sheet are subject to change without prior notice.



FEATURE

- 1. Ultra low and stable TCR performance
- 2. High power rating and compact size
- 3. High reliability and stability
- 4. Reduced size of final equipment
- 5. RoHS compliant and Lead free product
- 6. Low inductance below 3nH
- 7. Automotive AEC Q200 compliant

APPLICATION

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- Battery charger
- DC-DC power converter

DESCRIPTION

The resistors are constructed in a **high grade low resistive metal body**. The resistive layer is covered with a protective coat and printed a resistance marking code over it. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Lead-free terminations.



Fig 1. Construction of Chip-R

QUICK REFERENCE DATA

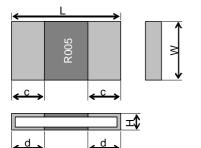
Item	General Specification
Series No.	WW25R
Size code	2512 (6432)
Resistance Tolerance	±5%, ±1%
Resistance Value	$0.0005\Omega, 0.001\Omega, 0.002\Omega, 0.003\Omega, 0.004\Omega,$
	$0.005\Omega, 0.006\Omega, 0.007\Omega, 0.008\Omega, 0.009\Omega, 0.010\Omega$
TCR (ppm/°C)	0.001Ω: ±100ppm; others: ±70ppm/°C
Max. dissipation at T _{amb} =70°C	2 W
Max. Operation Current	63.2A, 44.7A, 31.6A, 25.8A, 22.3A, 20A, 18.2A, 16.9A, 14.1A
Operation temperature	-55 ~ +155'C

Note :

1. Max. Operation Current : So called RCWC (Rated Continuous Working Current) is determined by

 $RCWC = \sqrt{Rated Power / Resistance Value}$

MECHANICAL DATA



Туре	Size (inch)	Resistance	L (mm)	W (mm)	H (mm)	c (mm)	d (mm)
		0.5mΩ		3.2±0.25	0.58±0.15		
		1mΩ	mΩ mΩ mΩ mΩ 6.3±0.25 mΩ	3.2±0.25	0.38±0.15		
		2mΩ			0.58±0.15	2.2±	0.25
		3mΩ			0.48±0.15		
	2512	4mΩ 2 5mΩ 6mΩ		4mΩ	0.37±0.15		
WW25R					0.51±0.15	1.1±	0.25
				3.1±0.25	0.48±0.15	1.05:	±0.25
		7mΩ			0.40±0.15	0.70:	±0.25
		8 mΩ	8 mΩ		0.35±0.15	1.10:	±0.25
		9 mΩ			0.35±0.15	0.80:	±0.25
		10mΩ				0.35±0.15	0.50:



MARKING

Each resistor is marked with a four-digit code on the protective coating to designate the nominal resistance value.

 $R005 = 5 m \Omega$ R001 = 1 m Ω

FUNCTIONAL DESCRIPTION

Derating curve

The power that the resistor can dissipate depends on the operating temperature; see Fig.2

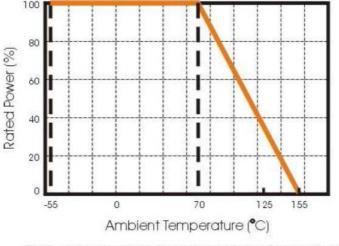


Fig.2 Maximum dissipation in percentage of rated power As a function of the ambient temperature

MOUNTING

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.



SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 3 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 3.

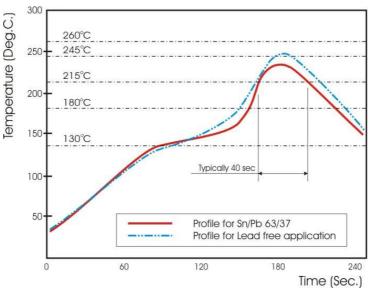


Fig 3. Infrared soldering profile for Chip Resistors WW25

CATALOGUE NUMBERS

The resistors have a catalogue number starting with .

WW25	R	R001	F	т	L	J
Size code WW25 : 2512	Type code R : 2W Sensing type	Resistance codeR is first digit followed by 3 significant digits. 0.001Ω = R001 0.005Ω = R005 0.010Ω = R010	Tolerance J : ±5% F : ±1%	Packaging code T : 7" Reel taping	Termination code L = Sn base (lead free)	Special code J = AEC Q200 compliant
		$0.0005\Omega = R0L5$				

Reeled tape packaging : 12mm width plastic emboss taping 4,000pcs per reel.

TEST AND REQUIREMENTS

TEST	PROCEDURE	REQUIREMENT
High temperature exposure	Ambient temperature 155±2°C, no load, 1000 hrs	no visible damage
MIL-STD-202-108		∆R/R max. ±3%
Temperature cycling	1. 30 minutes at -55°C±3°C,	no visible damage
JESD22 JA-104	2. 2~3 minutes at room temperature,	∆R/R max. ±1%
	3. 30 minutes at +125°±3°C,	
	4. 2~3 minutes at room temperature,	
	Total 1000 continuous cycles	
Bias Humidity	Condition: 85°C & 85% R.H.	no visible damage
MIL-STD-202-103	Test power: 10% of rated power shall be applied continuously. Duration 1000hrs	Δ R/R max. ±3%
Operational Life	Ambient temperature: 125±2°C	no visible damage
MIL-STD-202-108	The applied voltage shall be the voltage to be calculated at 35% of rated dissipation or the	Δ R/R max. ±3%
	limiting element voltage whichever is the smaller.	
	Condition: The voltage shall be applied continuously.	
	Duration: 1000 hrs	
Dimension	JESD22 Method JB-100	Meet dimension spec as defined in p.3
Resistance to Solvents	Solvent: 2–propanol at 25°C	Δ R/R: max ±1%
MIL-STD-202-215	Immersion time: 3 min Brush: 10 times brushing Immersion and brush cycle: 3cycle	No visible damage
Mechanical Shock MIL-STD-202-213	Waveform: half sine, Peak value100G, Normal duration 6ms Condition: XX'YY'ZZ', 10times each	Δ R/R: max. ±1% No visible damage
Vibration MIL-STD-202-204	Peak acceleration and Sweep time: 5 g's for 20 min , Frequency 10Hz to 2000Hz, Condition: 12 cycles each of 3 orientations	∆R/R: max ±1% No visible damage
Resistance to soldering heat	Un-mounted chips 10±0.5 seconds, 260±5°C	Δ R/R: max ±1%
MIL-STD-202-210		No visible damage
ESD test	Human body model, 2 Kohm, 150 pF,	Δ R/R: max ±1%
AEC Q200-002	Test voltage: 8KV	No visible damage
Solderability	a)4hrs / 155 $^\circ\!\!\mathbb{C}^*$ dry then solder dipping 235 $^\circ\!\!\mathbb{C}$ /5sec	good tinning (>95% covered)
J-STD-002	b)Steam 8 hrs then 215 $^\circ\!{\rm C}$ / 5sec solder dipping	no visible damage
	c)Steam 8 hrs then 260 $^\circ\!\mathrm{C}$ / 7sec solder dipping	The visible damage
Bending strength	Bending 2mm for 60 seconds.	Δ R/R: max ±1%
AEC Q200-005		No visible damage
Adhesion	Pressurizing force: 17.7N, Test time: 60±1s.	Δ R/R: max ±1%
AEC Q200-006		No visible damage

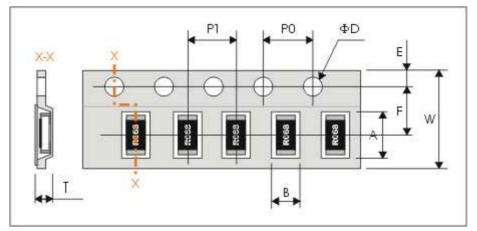
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Electrical Characterization	1. D.C. Res					As specified in
	Resistance value shall be measured by mounting the					specification
	substrate of	the following cor	ndition.			
	Current terminal		rrent minal	:Coppe	resist	
		145 		Un	itimm	
	Style	Resistance value(mΩ)	а	b	С	
	WW25R	1	1.5	3.0	4.0	
		0.5, 2 to 4	1.8	2.9	25	
		5 to 10	4.0	1.8	3.5	
	4-Terminal I Note: The m to DC Low c	f copper clad: 0.0 method, Measure neasuring appara ohm Meter (1A) o PORATION.	ement cu itus corre	sponding	,	
	2. Temperature Coefficient of Resistance					
	–55 ℃ / +20	℃ / +20 ℃ / +155%	С			

PACKAGING

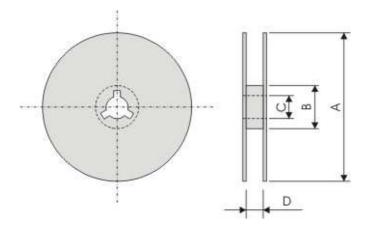
Plastic Tape specifications (unit :mm)



Symbol	А	В	W	F	E
Dimensions	6.90±0.20	3.60±0.20	12.00±0.30	5.50±0.1	1.75±0.10

Symbol	P1	P0	ΦD	Т
Dimensions	4.00±0.10	4.00±0.10	$\Phi 1.50^{+0.1}_{-0.0}$	1.10±0.15

Reel dimensions



Symbol	А	В	С	D
(unit : mm)	Ф180.0 -1.5	Φ60.0±1.0	13.0±0.2	13.0±1.0

Taping quantity

- Chip resistors 4,000 pcs per reel.